Renesas Electronics Reaches a Definitive Agreement to Transfer its Subsidiaries' Back-End Facilities and Others to J-Devices

TOKYO, Japan, March 19, 2013 - Renesas Electronics Corporation (TSE:6723, "Renesas"), a premier supplier of advanced semiconductor solutions, today announced that Renesas and J-Devices Corporation ("J-Devices") signed a definitive agreement ("DA") to transfer Renesas subsidiaries' back-end facilities and others to J-Devices following a Memorandum of Understanding which was announced on January 30, 2013 in the news release *"Renesas Electronics and J-Devices Sign Memorandum of Understanding on Transfer of Back-End Facilities*".

In this transfer, Renesas defines its wholly owned subsidiaries, Renesas Northern Japan Semiconductor, Inc. ("Renesas Northern Japan"), Renesas Kansai Semiconductor Co., Ltd. ("SKS"), Renesas Kyushu Semiconductor Corp. ("Renesas Kyushu") and Renesas Northern Japan's wholly owned subsidiary, Hokkai Electronics Co., Ltd. ("Hokkai Electronics") as "splitting companies in absorption-type split". Through an absorption-type corporate split ("the corporate split") Renesas will transfer assets, debts, other rights and obligations related to partial back-end production business of the splitting companies in absorption-type split (back-end production business of the Hakodate Factory of Renesas Northern Japan and the Fukui Factory of SKS, back-end production business and contract manufacturing service of the Kumamoto Factory of Renesas Kyushu, and production support business of Hokkai Electronics: referred to collectively below as "the business to be transferred") to a wholly owned subsidiary that Renesas will newly establish. Then Renesas will transfer all issued shares of the subsidiary to J-Devices (This transfer is referred to below as "the transfer").

The DA aims at building a long-term, mutually beneficial relationship between Renesas and J-Devices as strategic partners in the semiconductor production business. With today's agreement as the basis, the two companies intend to complete the transfer on June 1, 2013.

I. Purpose of the Corporate Split and the Transfer

As announced on July 3, 2012, in *"Renesas Electronics Announces the Direction of Various Measures to Establish Robust and Profitable Structure"*, Renesas is proceeding with the restructuring of Renesas group production facilities in Japan in order to strengthen its revenue base. As part of this process, under a production strategy in which the back-end facilities in Japan specialize in production of high-value added products with increasing outsourcing ratio as well as production ratio at Renesas overseas sites as a result, the Yonezawa Factory of Renesas Northern Japan and the Oita Factory of Renesas Semiconductor Kyushu Yamaguchi Co., Ltd. were to be maintained and strengthened, and the business to be transferred this time were to be "considered for transfer within one year" in a process of selection and focus of business operations. Accordingly, Renesas began looking for a transfer assignee with whom it could expect to build a long-term partnership that would strengthen the competitiveness of the business to be transferred and provide

a high-quality, reliable supply of products.

On the other hand, as a company devoted to semiconductor assembly and test operations for customers, J-Devices believed it is of the utmost importance to expand the scale of its operation in order to strengthen cost competitiveness required for the further business growth.

Against this background, Renesas and J-Devices came to a common understanding, and reached the DA regarding the business to be transferred to J-Devices on June 1, 2013.

The Renesas products, which are related to the business to be transferred, will continue to be supplied by Renesas to customers with the quality, delivery schedules, service equal to or better than before even after the transfer.

As previously mentioned, Renesas will transfer assets, debts, other rights and obligations related to the business to be transferred to a wholly owned subsidiary that Renesas will newly establish. Then Renesas will transfer all issued shares of the subsidiary to J-Devices. The overview of the subsidiary is as follows.

II. Establishment of the Subsidiary

- Purpose of the Establishment of the Subsidiary (Successor Company in Absorption-Type Split) As part of the transfer, Renesas intends to integrate the business to be transferred into Renesas J Semiconductor Corporation ("successor company in absorption-type split"), which Renesas will newly establish as its wholly owned subsidiary.
- 2. Overview of the Subsidiary to be Established in April 2012 as a Successor Company in Absorption-Type Split

Company Name	Renesas J Semiconductor Corporation	
Location	2-6-2, Ote-machi, Chiyoda-ku, Tokyo 100-0004, Japan	
Representative	Akira Furuki, Representative Director and President	
Major Operationa	Research, development, design, manufacture and sale of electronic	
Major Operations	products	
Capital	1 million yen	

- III. The Corporate Split
- 1. Outline of the Corporate Split
- (1) Timeline for the Corporate Split

Approval of the splitting companies in absorption-type split for the corporate split agreement: April 2013 (planned)

Approval of the successor company in absorption-type split for the corporate split agreement: April 2013 (planned)

Signing of the corporate split agreement: April 2013 (planned)

Approval of shareholders' meetings of the splitting companies in absorption-type split for the corporate split: May 2013 (planned)

Approval of shareholders' meeting of the successor company in absorption-type split for the corporate split: May 2013 (planned)Effective date of the corporate split: June 1, 2013 (planned)

(2) Method of the Corporate Split

Renesas Northern Japan, SKS, Renesas Kyushu and Hokkai Electronics will be the splitting companies in absorption-type split and Renesas J Semiconductor Corporation will be the successor company in absorption-type split.

(3) Share Allocation in Accordance with the Corporate Split

<Corporate split of Renesas Kyushu>

Upon the corporate split, the successor company in absorption-type split will issue 3,000 common stocks and will allocate all of them to Renesas Kyushu, a splitting company in absorption-type split. In addition, Renesas Kyushu will allocate all the shares as dividend of surplus to its wholly owning parent company, Renesas.

<Corporate split of other three companies (Renesas Northern Japan, SKS, and Hokkai Electronics) >

Upon the corporate split, allocation of shares, cash and other property is not scheduled.

(4) Share Subscription Rights and Bonds with Share Subscription Rights The splitting companies in absorption-type split have not issued share subscription rights and bonds with share subscription rights.

(5) Increase and Decrease in Capital Resulting from the Corporate Split

Capital of the splitting companies in absorption-type split will not be changed following the corporate split while capital of the successor company in absorption-type split will be increased by 300 million yen resulting from the corporate split of Renesas Kyushu.

(6) Rights and Obligations Transferred to the Successor Company

The successor company in absorption-type split will acquire assets, debts, other rights and obligations of the business to be transferred on the effective date of the corporation split based on the corporate split agreement with the splitting companies in absorption-type split. The transfer will be undertaken with the method of noncumulative taking of obligation.

(7) Ability to Fulfill Obligations

Renesas concludes that both the splitting companies and the successor company in absorption-type split shall have abilities to fulfill all their debt obligations on and after the effective date of the corporate split.

			any 1		cessor Company	
(4)		Renesas Northern Japan		Renesas	J Semiconductor	
(1)	Company Name	Semiconductor, Inc.		Corporation		
		145, Aza-Nakajima, N	lanae-cho,	262 Oto	machi. Chivada ku	
(2)	Location	Kameda-gun, Hokkai	do,		2-6-2, Ote-machi, Chiyoda-ku, Tokyo 100-0004, Japan	
I		041-1196, Japan			J-0004, Japan	
(2)	Representative	Kosuke Tanaka, Rep	resentative	Akira Furu	uki, Representative	
(3)	Representative	Director and Presider	nt	Director a	nd President	
		Research, developme	ent,	Research	, development, design,	
(4)	Major Operations	design, manufacture	and sale of	manufact	ure and sale of	
		semiconductor and IC	C products	electronic	products	
(5)	Capital	2,550 million yen		1 million y	ven	
(6)	Established	May 30, 1970		April, 201	3 (planned)	
(7)	Number of Shares	6,648,000				
(7)	Issued	0,040,000				
(8)	Fiscal Term	March 31		March 31		
(9)	Employees	—		_		
(10)	Main Client	—		—		
(11)	Main Bank	—		—		
(12)	Major Shareholders	Renesas Electronics		Renesas	Electronics Corporation	
(12)	and Equity Ratio	Corporation 100%		100%		
(13)	The financial results a	and financial position of	the splitting	company	or the past three years	
Accour	iting Period	Fiscal year ended	Fiscal yea	ar ended	Fiscal year ended	
Account		March 2010	March	2011	March 2012	
Net	Asset	9,380 million yen	9,827 n	nillion yen	8,031 million yen	
Tota	l Asset	31,335 million yen	30,421 n	nillion yen	31,117 million yen	
Net Asset Per Share		1,410.88 yen	1,478.16 yen		1,208.06 yen	
Net Sales		44,318 million yen	48,562 million yen		41,536 million yen	
Operating Income		1,162 million yen	2,143 n	nillion yen	-814 million yen	
Ordi	inary Income	1,043 million yen	2,064 n	nillion yen	-885 million yen	
Net	Income	1,901 million yen	447 n	nillion yen	-1,796 million yen	
Net	Income Per Share	285.94 yen		67.27 yen	-270.09 yen	
Divid	dends Per Share					

		Splitting Company 2	Successor Company
(1)	Company Name	Renesas Kansai	Renesas J Semiconductor

		Semiconductor Co., L	_td.	Corporatio	on
(2) Location		2-9-1 Seiran, Otsu-shi, Shiga		2-6-2, Ote-machi, Chiyoda-ku,	
(2)	(2) Location 520-855			Tokyo 100-0004, Japan	
		Yasuhiro Funakoshi,		Akira Euri	uki, Representative
(3)	Representative	Representative Direc	tor and		nd President
		President		Director a	nu i resident
		Research, developme	ent,	Research	, development, design,
(4)	Major Operations	design, manufacture	and sale of	manufact	ure and sale of
		semiconductor and IC	C products	electronic	products
(5)	Capital	1,000 million yen		1 million y	ren
(6)	Established	July 1, 1983		April, 201	3 (planned)
(7)	Number of Shares Issued	20,000		_	
(8)	Fiscal Term	March 31		March 31	
(9)	Employees	_		-	
(10)	Main Client	_		_	
(11)	Main Bank	—			
(10)	Major Shareholders	Renesas Electronics		Renesas	Electronics Corporation
(12)	and Equity Ratio	Corporation 100%		100%	
(13)	The financial results a	and financial position of	the splitting	company f	for the past three years
A	unting Dariad	Fiscal year ended	Fiscal yea	ar ended	Fiscal year ended
ACCOU	inting Period	March 2010	March	2011	March 2012
Ne	t Asset	1,871 million yen	1,866 r	nillion yen	560 million yen
Tot	al Asset	56,987 million yen	53,309 r	nillion yen	45,524 million yen
Ne	t Asset Per Share	93,555.32 yen	93,3	12.14 yen	28,016.53 yen
Net Sales		85,991 million yen	68,065 million yen		55,121 million yen
Operating Income		7,641 million yen	1,547 r	nillion yen	582 million yen
Ord	dinary Income	6,540 million yen	184 r	nillion yen	-639 million yen
Ne	t Income	3,584 million yen	-3.7 r	nillion yen	-1,307 million yen
Ne	t Income Per Share	179,219.92 yen	-1	85.74 yen	-65,325.00 yen
Div	vidends Per Share	_		_	_

		Splitting Company 3	Successor Company
(1)	Company Name	Renesas Kyushu	Renesas J Semiconductor
(1)	Company Name	Semiconductor Corp.	Corporation
		272-10, Oaza-Takaono,	2.6.2. Ota machi Chivada ku
(2)	Location	Ozu-machi, Kikuchi-gun,	2-6-2, Ote-machi, Chiyoda-ku,
		Kumamoto, 869-1232, Japan	Tokyo 100-0004, Japan

(0)	Representative	Akira Furuki, Represe	entative	Akira Furu	uki, Representative
(3)	Director	Director and President		Director and President	
		Research, development,		Research, development, design,	
(4)	Major Operations	design, manufacture	and sale of	manufact	ure and sale of
		semiconductor and IC	C products	electronic	products
(5)	Capital	500 million yen		1 million y	ren
(6)	Established	August 1, 1991		April, 201	3 (planned)
(7)	Number of Shares	7.000			
(7)	Issued	7,000		_	
(8)	Fiscal Term	March 31		March 31	
(9)	Employees	_		_	
(10)	Main Client	_		_	
(11)	Main Bank	_		_	
(10)	Major Shareholders	Renesas Electronics		Renesas Electronics Corporation	
(12)	and Equity Ratio Corporation 1			100%	
(13)	The financial results a	and financial position of the splitting company for the past three years			for the past three years
		Fiscal year ended	Fiscal yea	ar ended	Fiscal year ended
Accou	nting Period	March 2010	March	2011	March 2012
Net	t Asset	1,494 million yen	1,747 r	nillion yen	1,124 million yen
Tot	al Asset	20,863 million yen	22,012 r	nillion yen	18,232 million yen
Net	Net Asset Per Share 213,396.76 yen 249,6		18.47 yen	160,634.74 yen	
Net Sales		31,506 million yen	30,890 million yen		24,791 million yen
Operating Income		471 million yen	572 million yen		-348 million yen
Orc	dinary Income	367 million yen	468 r	nillion yen	-493 million yen
Net	t Income	241 million yen	253 r	nillion yen	-623 million yen
Net	t Income Per Share	34,447.75 yen	36,2	21.71 yen	-88,983.73 yen
Div	idends Per Share	_		_	_

		Splitting Company 4	Successor Company
(1)	Company Name	Hokkai Electronics Co., Ltd.	Renesas J Semiconductor Corporation
(2)	Location	289-12, Higashi-cho, Yakumo-cho, Futami-gun, Hokkaido, 049-3102, Japan	2-6-2, Ote-machi, Chiyoda-ku, Tokyo 100-0004, Japan
(3)	Representative	Keiichi Nakamura, Representative Director and President	Akira Furuki, Representative Director and President
(4)	Major Operations	Manufacture and sale of IC	Research, development, design,

		products			e and sale of
(5)	Capital	20 million yen		electronic p 1 million ye	
. ,	•			-	
(6)	Established	November 2, 1978		April, 2013	(planned)
(7)	Number of Shares	400		_	
~ /	Issued				
(8)	Fiscal Term	March 31		March 31	
(9)	Employees	—		—	
(10)	Main Client	—		—	
(11)	Main Bank	—		—	
(12)	Major Shareholders	Renesas Northern Ja	pan	Renesas Electronics Corporation	
(12)	and Equity Ratio	Semiconductor, Inc.	100%	100%	
(13)	The financial results a	and financial position of	the splitting	company fo	r the past three years
Accounting Period		Fiscal year ended	Fiscal ye	ear ended	Fiscal year ended
Accou	nung Penoa	March 2010	Marcl	n 2011	March 2012
Net	t Asset	62 million yen	70	million yen	75 million yen
Tot	al Asset	215 million yen	210	million yen	198 million yen
Net	t Asset Per Share	156,517.50 yen	175	405.00 yen	188,185.00 yen
Net	t Sales	308 million yen	310	million yen	262 million yen
Op	erating Income	13 million yen	20	million yen	18 million yen
Orc	dinary Income	16 million yen	20	million yen	16 million yen
Net	t Income	3 million yen	7	million yen	5 million yen
Net	t Income Per Share	8,139.99 yen	18	888.64 yen	12,779.84 yen
Div	vidends Per Share	_		_	

3. Overview of the Business to be Carved out through the Corporate Split

(1) Business to be Carved out

Hakodate Factory of Renesas Northern Japan: Semiconductor back-end production business Fukui Factory of SKS: Semiconductor back-end production business Kumamoto Factory of Renesas Kyushu: Semiconductor back-end production business and

contract manufacturing service

Hokkai Electronics: Support business of semiconductor back-end production

(2) Financial Results of Divisions to be Carved out

A. Hakodate Factory of Renesas Northern Japan

	Fiscal year ended March 2011	Fiscal year ended March 2012
Sales*	25,782 million yen	30,960 million yen

B. Fukui Factory of SKS

	Fiscal year ended March 2011	Fiscal year ended March 2012
Sales*	35,017 million yen	25,422 million yen

C. Kumamoto Factory of Renesas Kyushu

	Fiscal year ended March 2011	Fiscal year ended March 2012
Sales*	50,208 million yen	56,293 million yen

D. Hokkai Electronics

	Fiscal year ended March 2011	Fiscal year ended March 2012
Sales*	310 million yen	262 million yen

*Above sales include the value of chips and others which Renesas provides to each splitting company for profit.

(3) List of Assets and Liabilities to be Carved out and their Book Values (As of March 31, 2012)

	Assets	Li	abilities
Item	Book Value	Item	Book Value
Current Assets	624 million yen	Current Liabilities	6 million yen
Fixed Assets	4,195 million yen	Fixed Liabilities	3 million yen
Total	4,819 million yen	Total	9 million yen

A. Hakodate Factory of Renesas Northern Japan

B. Fukui Factory of SKS

	Assets	Li	abilities
Item	Book Value	Item	Book Value
Current Assets	1,213 million yen	Current Liabilities	1 million yen
Fixed Assets	4,869 million yen	Fixed Liabilities	0 million yen
Total	6,082 million yen	Total	1 million yen

C. Kumamoto Factory of Renesas Kyushu

	Assets	Li	abilities
Item	Book Value	Item	Book Value
Current Assets	1,909 million yen	Current Liabilities	0 million yen
Fixed Assets	9,911 million yen	Fixed Liabilities	44 million yen
Total	11,820 million yen	Total	44 million yen

D. Hokkai Electronics

	Assets	Li	abilities
ltem	Book Value	Item	Book Value
Current Assets	0 million yen	Current Liabilities	0 million yen
Fixed Assets	2 million yen	Fixed Liabilities	0 million yen
Total	2 million yen	Total	0 million yen

* After March 31, 2012, the splitting companies had 7 billion yen of fixed liability of which Renesas becomes the creditor. 7 billion of fixed liability has the equivalent effect as the future

payment for the transferred company.

- 4. Status of the Splitting Companies and the Successor Company Following the Corporate Split
- (1) Status of the Splitting Companies

There will be no changes to company names, major operations, capital and fiscal terms of the splitting companies (Renesas Northern Japan, SKS, Renesas Kyushu and Hokkai Electronics) following the corporate split. Representatives and locations of the companies are subject to change.

Company Name* ¹	Renesas J Semiconductor Corporation	
Location*1	2-6-2, Ote-machi, Chiyoda-ku, Tokyo 100-0004, Japan	
Representative	Akira Furuki, Representative Director and President	
Major Operations	Research, development, design, manufacture and sale of electronic	
	products	
Capital* ²	301 million yen	
Fiscal Term	March 31	
Net Asset	Not fixed yet at the moment	
Total Asset	Not fixed yet at the moment	

(2) Status of the Successor Company (Planned to be Established in April 2013)

Note 1: The successor company's name and location will be changed on the effective date of the transfer. (The name is scheduled to change to J-Devices Semiconductor Corporation.)

Note 2: The successor company's capital will be increased by 300 million yen following the corporate split.

5. Financial Outlook

The splitting companies and the successor company in absorption-type split are wholly owned subsidiaries of Renesas, thereby there will be no impact to Renesas' consolidated financial results.

IV. The Transfer

1. Purpose of the Transfer

Please refer to "*I. Purpose of the Corporate Split and the Transfer*". The transfer will be completed on condition that the corporate split, which was previously mentioned in "*III. The Corporate Split*", will be come into force.

(1) Company Name ^{*1}	Renesas J Semiconductor Corporation
(2) Location ^{*1}	2-6-2, Ote-machi, Chiyoda-ku, Tokyo 100-0004, Japan

(3)	Representative*1	Akira Furuki, R	eprese	ntative Director and Pre	esident
(4)	Major Operations	Research, development, design, manufacture and sale of electronic products			
(5)	Capital*2	301 million yer	۱		
(6)	Established	April 2013 (pla	nned)		
(7)	Major Shareholders and Equity Ratio	Renesas Electronics Corporation 100%			
		Capital Relationships	This company will be a Renesas' wholly owned consolidated subsidiary to be established in April 2013.		
(8)	Relationships between Related Parties	Personnel Relationships	There is no personnel relationship between Renesas and this company required to be referred to herein. A representative director of Renesas Kyushu, a Renesas subsidiary, will concurrently serve as a representative director of this company.		
		Business	There is no business relationship between Renesas		
		Relationships and this company required to be referred to herein.			
(9)	The financial results a	nd financial pos	ition of t	he company for the pa	st three years* ³
	Accounting Period	Fiscal year e	nded	Fiscal year ended	Fiscal year ended
	Accounting r enou	March 201	12	March 2011	March 2010
Net A	Asset			_	_
Total	Asset			_	—
Net A	sset Per Share			_	—
Net S	Sales				_
Oper	ating Income				_
Ordir	nary Income				—
Net l	ncome				_
Net l	ncome Per Share				_
Divid	ends Per Share	—		_	—

Note 1: The company's name, location and representative will be changed on the effective date of the transfer. (The name is scheduled to change to J-Devices Semiconductor Corporation.)
Note 2: The company's capital will be increased by 300 million yen following the corporate split.
Note 3: Since the company is planned to be established in April 2013, no financial results and financial position for the past three years are available.

3. Overview of the Transferee

(1) Company Name	J-Devices Corporation
(2) Location	1913-2 Fukura, Usuki-shi, Oita, Japan

(3)	Representative	CEO: Yoshifumi Nakaya				
(4)			nufacturing of semiconductor devices (Wafer test,			
	Major Operations	Assembly and Final test)				
(5)	Capital	1.77 billion yen	,			
(6)	Established	November 6, 1	970			
(7)	Net Asset	7.3 billion yen				
(8)	Total Asset	27.4 billion yen	1			
		Yoshifumi Naka	aya, etc.* ¹ 60.0%			
(9)	Major Shareholders	Amkor Technol	ogy Inc. 30.0%			
	and Equity Ratio	Toshiba Corporation 10.0%				
			There is no capital relationship between Renesas and			
		Capital	J-Devices required to be referred to herein. There is			
		Relationships	no capital relationship between affiliates of Renesas			
			and J-Devices required to be referred to herein.			
		Personnel Relationships	There is no personnel relationship between Renesas			
			and J-Devices required to be referred to herein. There			
			is no personnel relationship between affiliates of			
	Relationships		Renesas and J-Devices required to be referred to			
(10)	between Related		herein.			
	Parties		There is no business relationship between Renesas			
		Business	and J-Devices required to be referred to herein. There			
		Relationships	is no business relationship between affiliates of			
		relationships	Renesas and J-Devices required to be referred to			
			herein.			
		Status of	Renesas is not deemed to be a related party of			
		Related	J-Devices. Affiliates of Renesas are not deemed to be			
		Parties	a related party of affiliates of J-Devices.			

Note 1: Existing shareholders who invested before the capital injection from Amkor Technology Inc.

		3,010
(1)	Shares before the	(Number of voting rights: 3,010)
	Transfer	(Ratio of voting rights: 100%)
(0)	Shares to be	3,010
(2)	Transferred	(Number of voting rights: 3,010)
		4.8 billion yen (Value of common stocks of the successor company)
(3)	Transfer Price	
		Note: After March 31, 2012, the splitting companies had 7 billion yen

4. Number of Shares to be Transferred, Transfer Price, and Status of Shares after the Transfer

		of fixed liability of which Renesas becomes the creditor. 7 billion of fixed liability has the equivalent effect as the future payment for the transferred company.
(4)	Shares after the Transfer	0 (Number of voting rights: 0)
		(Ratio of voting rights: 0%)

5. Timeline for the Transfer

Approval of Board of the Directors for the share transfer agreement: March 19, 2013 Signing of the share transfer agreement: March 19, 2013 Date of the share transfer: June 1, 2013 (planned)

6. Financial Outlook

Renesas recorded 7 billion yen impairment loss from reduced book values of tangible and intangible fixed assets and others related to the business to be transferred in the third quarter of the fiscal year ending March 31, 2013. Thus the impact from the transfer is already counted into Renesas' financial forecasts for the fiscal year ending March 31, 2013.

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About Renesas Electronics Corporation

Renesas Electronics Corporation (TSE: 6723), the world's number one supplier of microcontrollers, is a premiere supplier of advanced semiconductor solutions including microcontrollers, SoC solutions and a broad-range of analog and power devices. Business operations began as Renesas Electronics in April 2010 through the integration of NEC Electronics Corporation (TSE: 6723) and Renesas Technology Corp., with operations spanning research, development, design and manufacturing for a wide range of applications. Headquartered in Japan, Renesas Electronics has subsidiaries in 20 countries worldwide. More information can be found at www.renesas.com.

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